HARRIS

HA-2650/55

Dual High Performance Operational Amplifier

Not Recommended For New Designs See HA-5102 or HA-5152

T-79-05-20

Features

- SLEW RATE 5V/μs
- BANDWIDTH 8MHz
- BIAS CURRENT 35nA
- AVG. OFFSET VOLTAGE DRIFT 8μV/°C
- POWER CONSUMPTION 75mW
- SUPPLY VOLTAGE RANGE ±2V TO ±20V

Applications

- VIDEO AMPLIFIERS
- HIGH IMPEDANCE, WIDEBAND BUFFERS
- INTEGRATORS
- AUDIO AMPLIFIERS
- ACTIVE FILTERS

Description

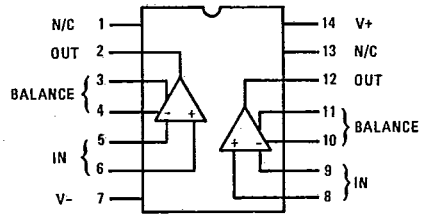
HA-2650/2655 contains two internally compensated operational amplifiers offering high slew rate and high frequency performance combined with exceptional DC characteristics. 5V/μsec slew rate and 8MHz bandwidth make these amplifiers suitable for processing fast, wideband signals extending into the video frequency spectrum. Signal processing accuracy is enhanced by front-end performance that includes 1.5mV offset voltage, 8μV/°C offset voltage drift and low offset and bias current (1nA and 35nA respectively). Offset voltage can be trimmed to zero on the devices offered in dual-in-line packages. Signal conditioning is further enhanced by 500MΩ input impedance.

Applications for HA-2650/2655 include video circuit designs such as high impedance buffers, integrators, tone generators and filters. These amplifiers are also ideal components for active filtering of audio and voice signals.

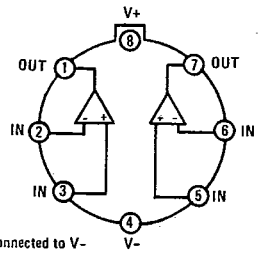
HA-2650/2655 are offered in 14 pin DIP and metal TO-99 packages and are also available in dice form. HA-2650 is specified form -55°C to +125°C. HA-2655 operates from 0°C to +75°C.

Pinouts

HA1-2650/2655 (CERAMIC DIP)
TOP VIEW

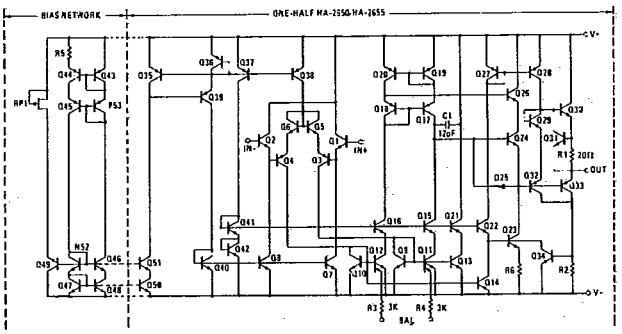


HA2-2650/2655 (TO-99 METAL CAN)
TOP VIEW



NOTE: Case Connected to V-

Schematic



Absolute Maximum Ratings (Note 1)

T_A = +25°C, Unless Otherwise Specified
Voltage Between V+ and V- Terminals 40V
Differential Input Voltage..... ±30V
Input Voltage (Note 1) ..... ±15V
Output Short Circuit Duration ..... Indefinite
Power Dissipation (Note 2)
TO-99 ..... 300mW

Operating Temperature Ranges

HA-2650 ..... -55°C ≤ T_A ≤ +125°C
HA-2655 ..... 0°C ≤ T_A ≤ +75°C
Storage Temperature Range:..... -65°C ≤ T_A ≤ +150°C

Electrical Specifications

V+ = +15V D.C., V- = -15V D.C.

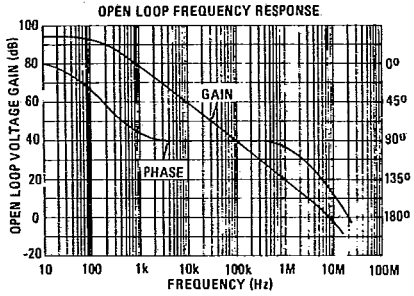
PARAMETER	TEMP.	HA-2650 -55°C to +125°C MIN.	HA-2650 -55°C to +125°C TYP.	HA-2650 -55°C to +125°C MAX.	HA-2655 0°C to +75°C MIN.	HA-2655 0°C to +75°C TYP.	HA-2655 0°C to +75°C MAX.	UNITS
INPUT CHARACTERISTICS								
Offset Voltage	+25°C		1.5	3		2	5	mV
	Full			5			7	mV
Av. Offset Voltage Drift	Full		8			8		µV/°C
Bias Current	+25°C		35	100		50	200	nA
	Full			200			300	nA
Offset Current	+25°C		1	30		2	60	nA
	Full			60			100	nA
Common Mode Range	Full	±13			±13			V
Differential Input Resistance (Note 9)	+25°C	5	20		5	20		MΩ
Common Mode Input Resistance	+25°C		500			500		MΩ
Input Capacitance	+25°C		5			5		pF
TRANSFER CHARACTERISTICS								
Large Signal Voltage Gain (Note 3ab)	+25°C	20K	40K		15K	40K		V/V
	Full	15K			10K			V/V
Common Mode Rejection Ratio (Note 4)	+25°C	80	100		74	100		dB
	Full	80			74			dB
OUTPUT CHARACTERISTICS								
Output Voltage Swing (Note 3c)	+25°C	±13	±14		±13	±14		V
	Full	±13			±13			V
Full Power Bandwidth (Notes 5 & 10)	+25°C	30	80		30	80		KHz
Output Current (Note 3a)	+25°C		±20			±18		mA
Output Resistance	+25°C		100			100		Ω
TRANSIENT RESPONSE (Note 6)								
Rise Time (Note 7)	+25°C		40	80		40	90	ns
Overshoot (Note 7)	+25°C		15	40		15	40	%
Slew Rate	+25°C	±2	±5		±2	±5		V/µs
POWER SUPPLY CHARACTERISTICS								
Supply Current	+25°C		2.5	4		3	5	mA
Power Supply Rejection Ratio (Note 8)	+25°C	80	100		74	100		dB
	Full	80			74			dB

NOTES:
1. For supply voltages less than ±15V, the absolute maximum input voltage is equal to the supply voltage.
2. Derate at 4.7mW/°C at ambient temperatures above +110°C.
3. (a) V_O = ±10V (b) R_L = 2K (c) R_L = 10K
4. V_{CM} = ±5.0V
5. A_V = 1, R_L = 2K, V_O = 20V_{pp}
6. See transient response/slew rate circuit.
7. V_{in} = 200mV
8. Δ V = ±5.0V
9. This parameter value based upon design calculations.
10. Full power bandwidth guaranteed based upon slew rate measurement FPBW = S.R./2πV_{peak}.

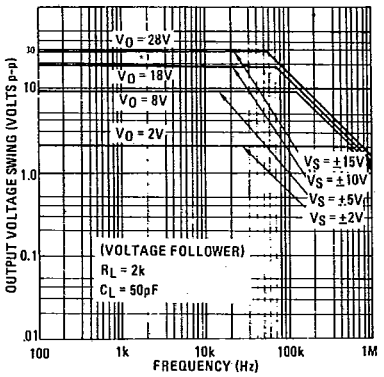
Typical Performance Curves

V+ = +15V, V- = -15V, T_A = +25°C, Unless Otherwise Specified.

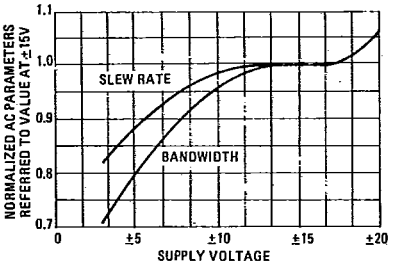
OPEN LOOP FREQUENCY RESPONSE



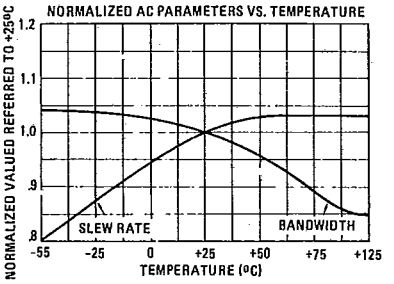
OUTPUT VOLTAGE SWING VS. FREQUENCY



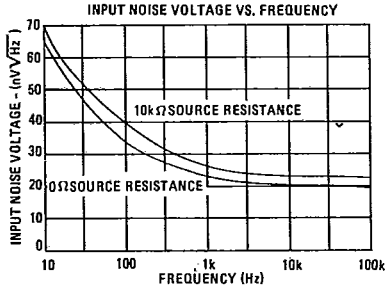
NORMALIZED AC PARAMETERS VS. SUPPLY VOLTAGE



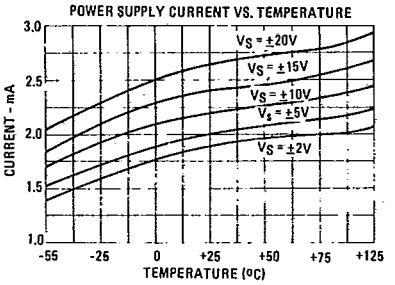
NORMALIZED AC PARAMETERS VS. TEMPERATURE



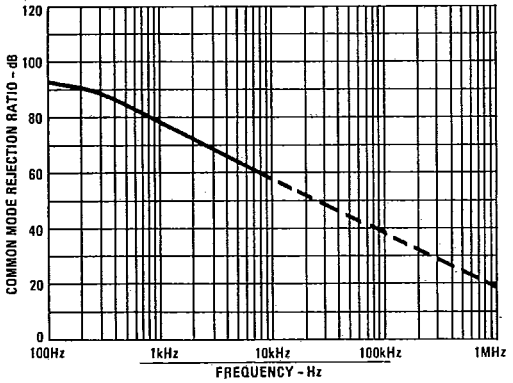
INPUT NOISE VOLTAGE VS. FREQUENCY



POWER SUPPLY CURRENT VS. TEMPERATURE

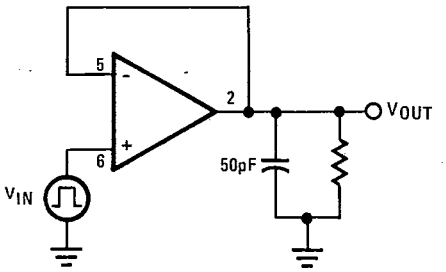


COMMON MODE REJECTION RATIO VS. FREQUENCY

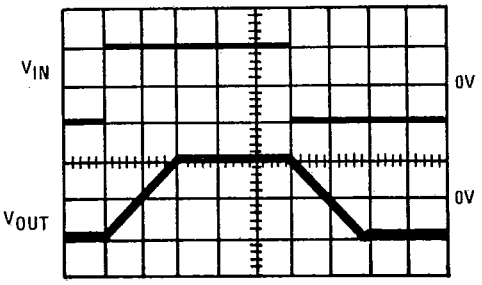


Test Circuits

TRANSIENT RESPONSE/SLEW RATE CIRCUIT



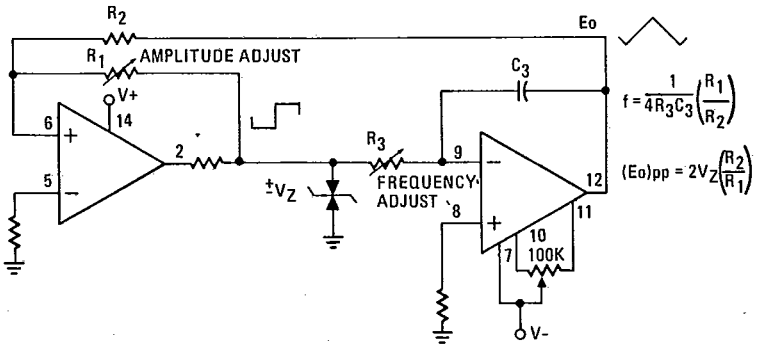
SLEWING WAVEFORM



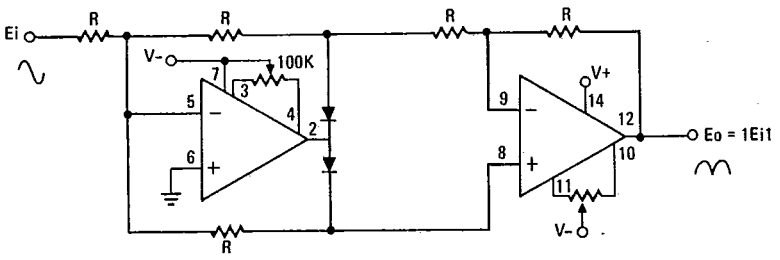
VERTICAL 5V/DIV. HORIZONTAL 1μs/DIV.

Typical Applications

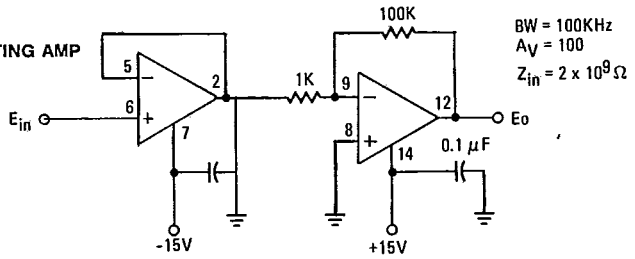
LOW COST HIGH FREQUENCY GENERATOR



ABSOLUTE - VALUE CIRCUIT



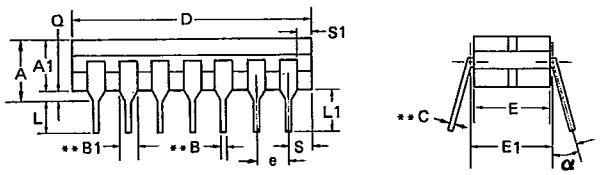
HIGH IMPEDANCE
HIGH GAIN
HIGH FREQUENCY INVERTING AMP



Package Configuration

T-90-20

A B C D E .300 CERAMIC DUAL-IN-LINE



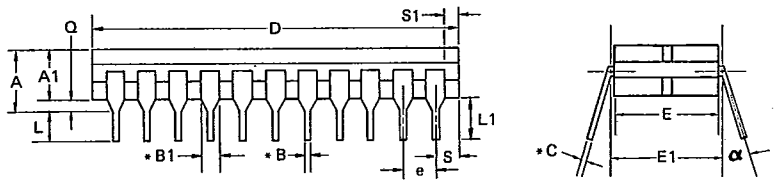
PKG. CODE	LEAD COUNT	DIM. A	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. L1	DIM. S	DIM. S1	DIM. Q	DIM. α
A	8 SSI	— .200	.140 .160	.016 .023	.050 .065	.008 .015	.375 .395	.245 .265	.290 .310	.100 BSC	.125 .150	.150 —	— .055	.005 —	.015 .060	0° 15°
B1	14 MSI	— .200	.140 .170	.016 .023	.050 .065	.008 .015	.753 .785	.265 .285	.290 .310	.100 BSC	.125 .180	.150 —	— .098	.005 —	.015 .060	0° 15°
B2	14 LSI	— .200	.140 .170	.016 .023	.050 .065	.008 .015	.753 .785	.285 .305	.300 .320	.100 BSC	.125 .180	.150 —	— .098	.005 —	.015 .060	0° 15°
C1	16* MSI	— .200	.140 .170	.016 .023	.050* .065*	.008 .015	.753 .785	.265 .285	.290 .310	.100 BSC	.125 .180	.150 —	— .080	.005 —	.015 .060	0° 15°
C2	16* LSI	— .200	.140 .170	.016 .023	.050* .065*	.008 .015	.753 .785	.285 .305	.300 .320	.100 BSC	.125 .180	.150 —	— .080	.005 —	.015 .060	0° 15°
D	18 LSI	— .200	.140 .170	.016 .023	.050* .065*	.008 .015	.882 .915	.285 .305	.300 .320	.100 BSC	.125 .180	.150 —	— .098	.005 —	.015 .060	0° 15°
E	20 LSI	— .200	.140 .170	.016 .023	.050* .065*	.008 .015	.940 .970	.285 .305	.300 .320	.100 BSC	.125 .180	.150 —	— .080	.005 —	.015 .060	0° 15°

* End leads are half leads where B remains the same and B1 is $\frac{0.035}{0.045}$

** Solder dip finish add +0.003 inches

F .400 CERAMIC DUAL-IN-LINE

G H .600 CERAMIC DUAL-IN-LINE



PKG. CODE	LEAD COUNT	DIM. A	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. L1	DIM. S	DIM. S1	DIM. Q	DIM. α
F .400	22 LSI	— .225	.150 .180	.016 .023	.050 .065	.008 .015	1.055 1.085	.375 .395	.395 .415	.100 BSC	.125 .180	.150 —	— .080	.005 —	.015 .060	0° 15°
G .600	24 LSI	— .225	.150 .180	.016 .023	.050 .065	.008 .015	1.24 1.27	.515 .535	.595 .615	.100 BSC	.125 .180	.150 —	— .098	.005 —	.015 .060	0° 15°
H .600	28 LSI	— .225	.160 .190	.016 .023	.050 .065	.008 .015	1.44 1.47	.515 .535	.595 .615	.100 BSC	.125 .180	.150 —	— .098	.005 —	.015 .060	0° 15°

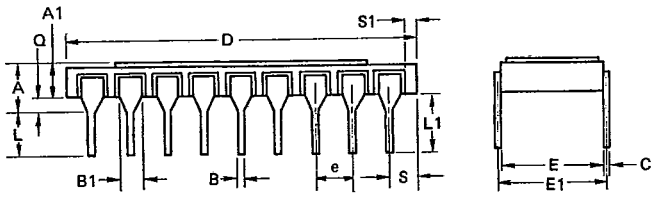
* Solder dip finish add +0.003 inches.

NOTE: Dimensions are $\frac{\text{Min}}{\text{Max}}$. Dimensions are in inches. BSC means basic spacing between centerlines.

Package Configuration

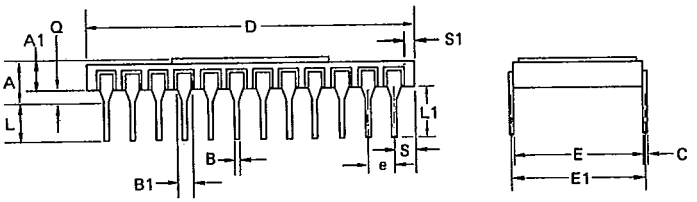
T-90-20

I .300 SIDEBRAZE DUAL-IN-LINE



PKG. CODE	LEAD COUNT	DIM. A	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. L1	DIM. S	DIM. S1	DIM. Q
I	18	— .200	.080 .110	.016 .023	.045 .060	.008 .015	.890 .910	.280 .300	.290 .310	.100 BSC	.125 .180	.150 —	— .098	.005 —	.025 .045

J K L .600 SIDEBRAZE DUAL-IN-LINE



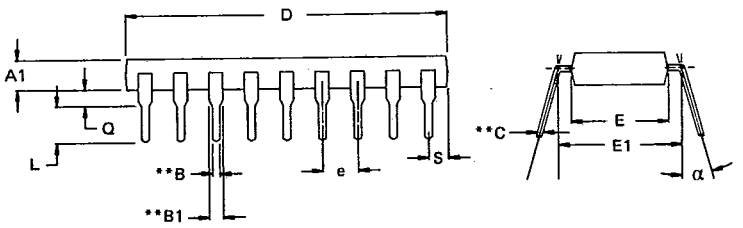
PKG. CODE	LEAD COUNT	DIM. A	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. L1	DIM. S	DIM. S1	DIM. Q
J	24	— .225	.080 .110	.016 .023	.040 .054	.008 .015	1.185 1.215	.587 .603	.598 .612	.100 BSC	.125 .180	.150 —	— .080	.005 —	.040 .060
K	28	— .225	.080 .110	.016 .023	.040 .054	.008 .015	1.385 1.415	.587 .603	.598 .612	.100 BSC	.125 .180	.150 —	— .080	.005 —	.030 .060
L	40	— .225	.080 .110	.016 .023	.040 .054	.008 .015	1.980 2.020	.587 .603	.598 .612	.100 BSC	.125 .180	.150 —	— .080	.005 —	.040 .060

NOTE: Dimensions are $\frac{\text{Min}}{\text{Max}}$. Dimensions are in inches.

BSC means basic spacing between centerlines.

Package Configuration

M N O P Q .300 PLASTIC DUAL-IN-LINE

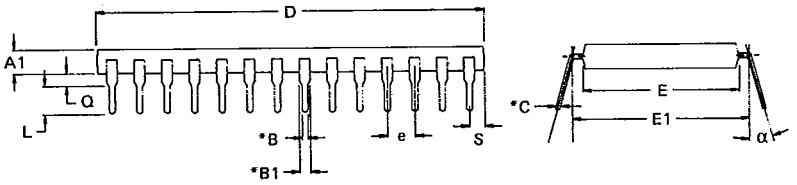


PKG. CODE	LEAD COUNT	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. S	DIM. Q	DIM. α
M	8	.125/.140	.016/.023	.050/.070	.008/.015	.370/.390	.245/.265	.290/.310	.090/.110	.110/.150	.030/.050	.020/.040	0°/15°
N	14	.125/.140	.016/.023	.050/.070	.008/.015	.750/.770	.245/.265	.290/.310	.090/.110	.110/.150	.030/.050	.020/.040	0°/15°
O	16*	.125/.140	.016/.023	.050/.070	.008/.015	.750/.770	.245/.265	.290/.310	.090/.110	.110/.150	.025/.035	.020/.040	0°/15°
P	18	.125/.140	.016/.023	.050/.070	.008/.015	.900/.920	.245/.265	.290/.310	.090/.110	.110/.150	.040/.060	.020/.040	0°/15°
Q	20	.130/.145	.016/.023	.050/.070	.008/.015	1.030/1.050	.250/.270	.290/.310	.090/.110	.110/.150	.060/.080	.020/.040	0°/15°

* End leads are half leads where B remains the same and B1 is 0.035/0.045

** Solder dip finish add 0.003 inches.

R S .600 PLASTIC DUAL-IN-LINE



PKG. CODE	LEAD COUNT	DIM. A1	DIM. B	DIM. B1	DIM. C	DIM. D	DIM. E	DIM. E1	DIM. e	DIM. L	DIM. S	DIM. Q	DIM. α
R	24	.145/.155	.016/.023	.050/.070	.008/.015	1.24/1.26	.540/.560	.590/.610	.090/.110	.110/.150	.045/.095	.020/.040	0°/15°
S	28	.145/.155	.016/.023	.050/.070	.008/.015	1.54/1.57	.540/.560	.590/.610	.090/.110	.110/.150	.110/.160	.020/.040	0°/15°

* Solder dip finish add 0.003 inches.

NOTE: Dimensions are Min/Max. Dimensions are in inches.

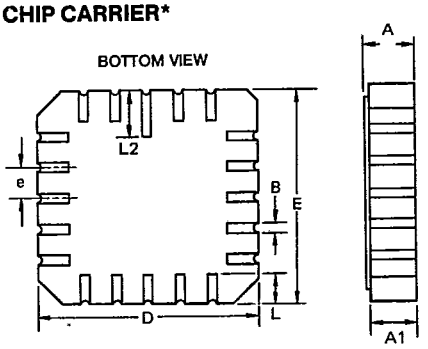
BSC means basic spacing between centerlines.

Package Configuration

T .350 CERAMIC LEADLESS CHIP CARRIER*

U .450 CERAMIC LEADLESS CHIP CARRIER*

V .650 CERAMIC LEADLESS CHIP CARRIER*

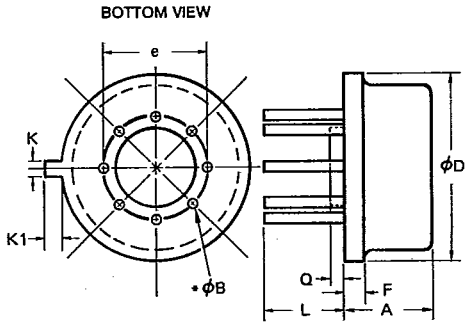


PKG. CODE	LEAD COUNT	DIM. A	DIM. A1	DIM. B	DIM. D	DIM. E	DIM. e	DIM. L	DIM. L2
T	20 .350 SQ	.073 .089	.063 .077	.022 .028	.342 .358	.342 .358	.050 BSC	.045 .055	.075 .095
U	28 .450 SQ	.074 .088	.064 .076	.022 .028	.442 .458	.442 .458	.050 BSC	.045 .055	.075 .095
V	44 .650 SQ	.073 .089	.063 .077	.022 .028	.643 .662	.643 .662	.050 BSC	.045 .055	.075 .095

* Solder dip finish for military parts conform to MIL-M-38510, Type A.

W TO-99 METAL CAN

X TO-100 METAL CAN



PKG. CODE	LEAD COUNT	DIM. A	DIM. ϕB	DIM. ϕD	DIM. e	DIM. F	DIM. K	DIM. K1	DIM. L	DIM. Q
W	8 TO-99	.165 .185	.016 .018	.345 .365	.190 .210	.020 .040	.028 .034	.028 .040	.505 .550	.015 .040
X	10 TO-100	.165 .185	.016 .018	.345 .365	.220 .240	.020 .040	.028 .034	.028 .040	.505 .550	.015 .040

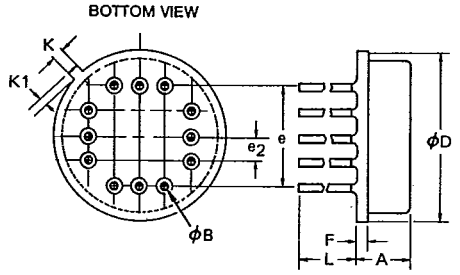
* Solder dip finish add +0.003 inches.

NOTE: Dimensions are Min/Max. Dimensions are in inches.

BSC means basic spacing between centerlines.

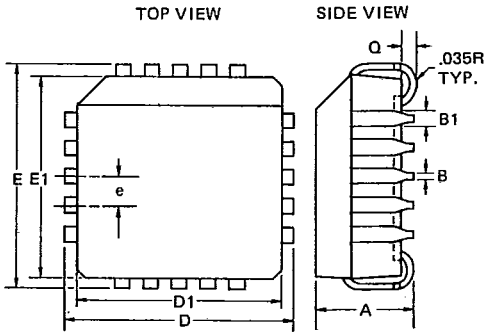
Package Configuration

Y TO-8 METAL CAN



PKG. CODE	LEAD COUNT	DIM. A	DIM. ϕB	DIM. ϕD	DIM. e	DIM. e2	DIM. F	DIM. K	DIM. K1	DIM. L
Y	12 TO-8	.130/.150	.016/.021	.585/.615	.400 BSC	.100 BSC	.020/.040	.027/.034	.027/.045	.500/.550

AA AB AC PLASTIC LEADED CHIP CARRIER



PKG. CODE	LEAD COUNT	DIM. A	DIM. B	DIM. B1	DIM. D/E	DIM. D1/E1	DIM. e	DIM. Q
AA	20	.165/.180	.013/.021	.026/.032	.385/.395	.350/.356	.050 BSC	.020/—
AB	28	.165/.180	.013/.021	.026/.032	.485/.495	.450/.456	.050 BSC	.020/—
AC	44	.165/.180	.013/.021	.026/.032	.685/.695	.650/.656	.050 BSC	.020/—

NOTE: Dimensions are Min/Max. Dimensions are in inches. BSC means basic spacing between centerlines.